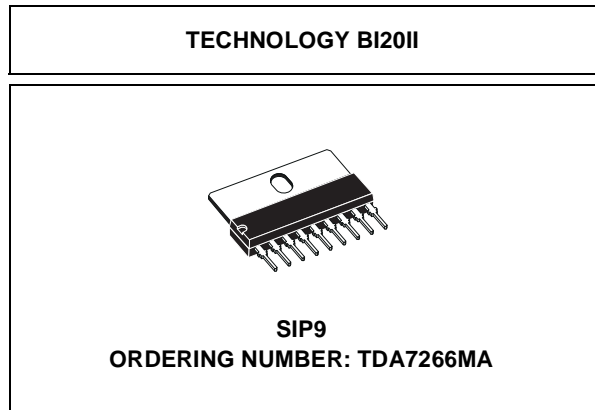




TDA7266MA

7W MONO BRIDGE AMPLIFIER

- WIDE SUPPLY VOLTAGE RANGE (3-18V)
- MINIMUM EXTERNAL COMPONENTS
 - NO SWR CAPACITOR
 - NO BOOTSTRAP
 - NO BOUCHEROT CELLS
 - INTERNALLY FIXED GAIN
- STAND-BY & MUTE FUNCTIONS
- SHORT CIRCUIT PROTECTION
- THERMAL OVERLOAD PROTECTION

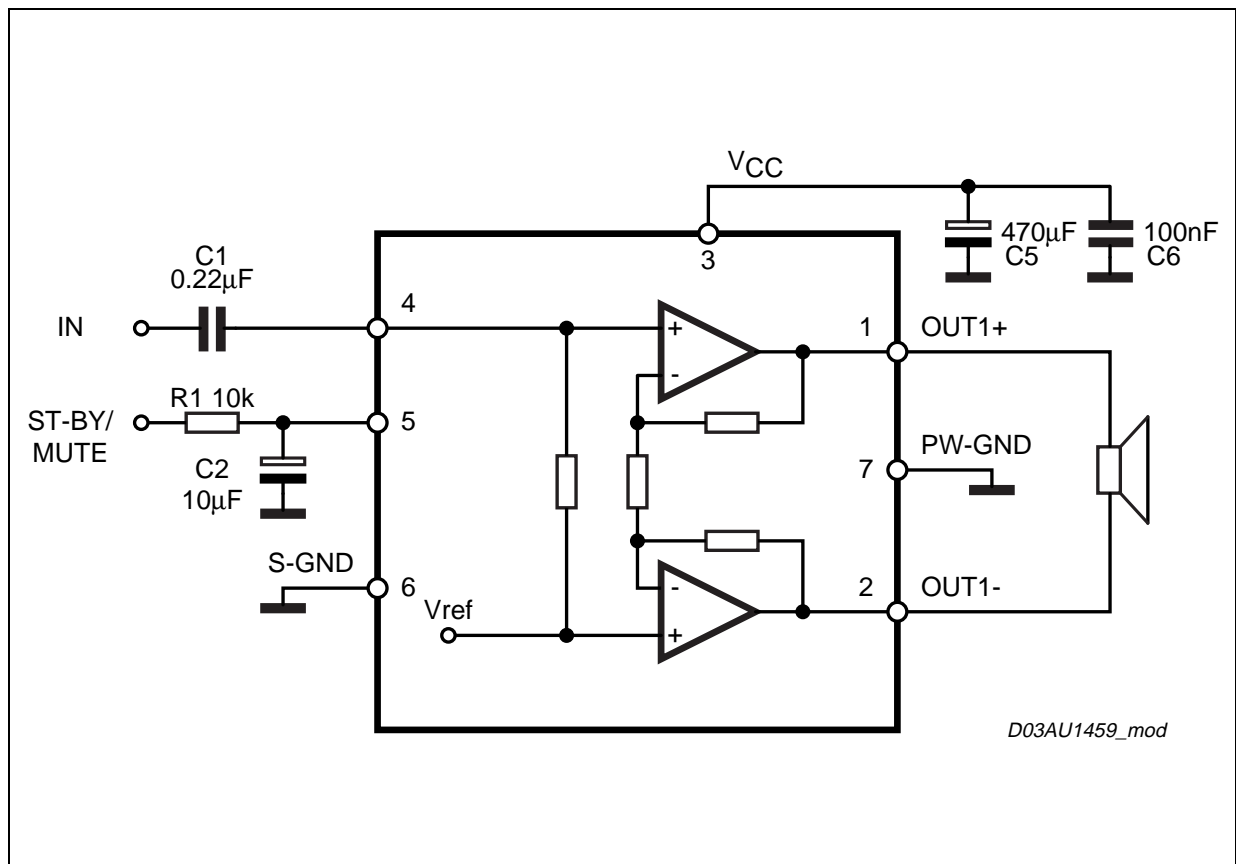


DESCRIPTION

The TDA7266MA is a mono bridge amplifier specially designed for TV and Portable Radio applications.

Pin to pin compatible with: TDA7266S, TDA7266, TDA7266M, TDA7266MA, TDA7266B, TDA7297SA & TDA7297.

Figure 1. Block and Application Diagram



TDA7266MA

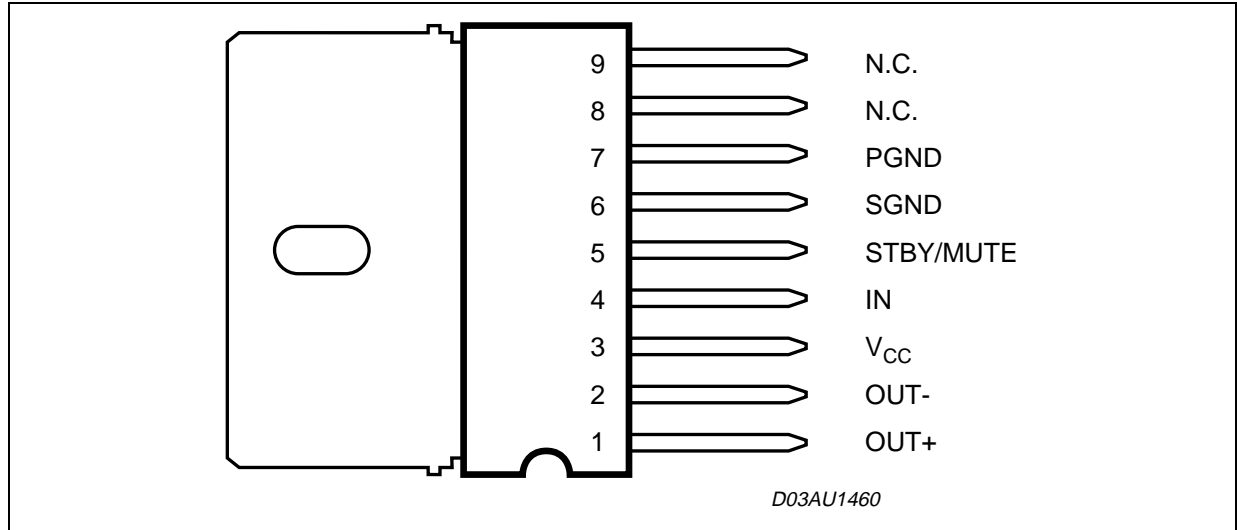
ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|----------------|--|------------|------|
| V_s | Supply Voltage | 20 | V |
| I_O | Output Peak Current (internally limited) | 2 | A |
| T_{op} | Operating Temperature | 0 to 70 | °C |
| T_{stg}, T_j | Storage and Junction Temperature | -40 to 150 | °C |

THERMAL DATA

| Symbol | Parameter | Value | Unit |
|------------------|----------------------------------|-------|------|
| $R_{th\ j-case}$ | Thermal Resistance Junction-case | 9 | °C/W |

PIN CONNECTION (Top view)



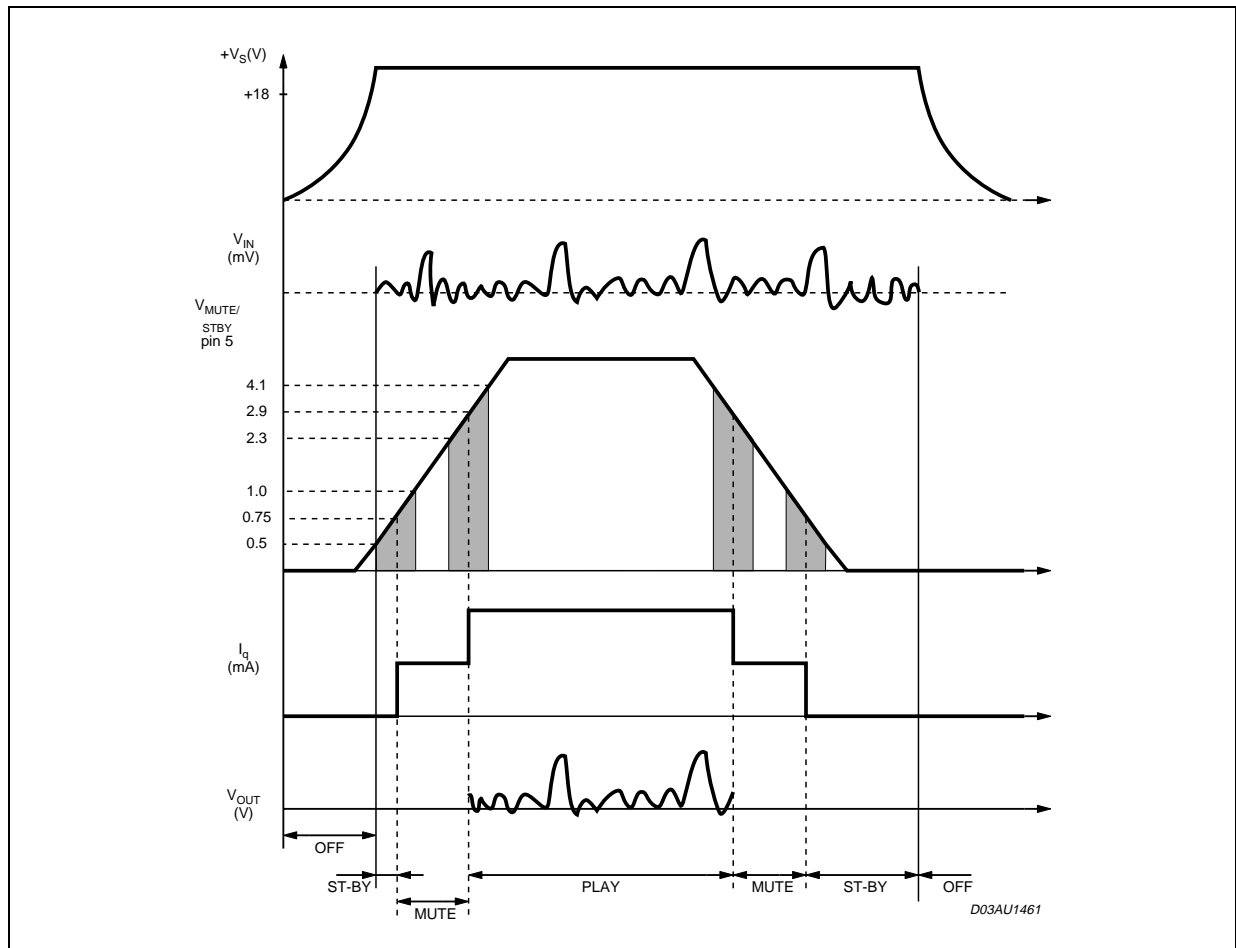
ELECTRICAL CHARACTERISTICS

($V_{CC} = 11V$, $R_L = 8\Omega$, $f = 1KHz$, $T_{amb} = 25^\circ C$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|------------|---------------------------|--|------|------|------|------------|
| V_{CC} | Supply Range | | 3 | 11 | 18 | V |
| I_q | Total Quiescent Current | | | 50 | 65 | mA |
| V_{OS} | Output Offset Voltage | | | | 120 | mV |
| P_O | Output Power | THD 10% | 6.3 | 7 | | W |
| THD | Total Harmonic Distortion | $P_O = 1W$ | | 0.05 | 0.2 | % |
| | | $P_O = 0.1W$ to $2W$ $f = 100Hz$ to $15KHz$ | | | 1 | % |
| SVR | Supply Voltage Rejection | $f = 100Hz$, $V_R = 0.5V$ | 40 | 56 | | dB |
| A_{MUTE} | Mute Attenuation | | 60 | 80 | | dB |
| T_w | Thermal Threshold | | | 150 | | °C |
| G_V | Closed Loop Voltage Gain | | 25 | 26 | 27 | dB |
| R_i | Input Resistance | | 25 | 30 | | K Ω |

ELECTRICAL CHARACTERISTICS (continued)(V_{CC} = 11V, R_L = 8Ω, f = 1KHz, T_{amb} = 25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|---------------------|------------------------|--|-----------------------|-------------------------|-------------------------|------|
| VT _{MUTE} | Mute Threshold | for V _{CC} > 6.4V; Vo = -30dB | 2.3 | 2.9 | 4.1 | V |
| | | for V _{CC} < 6.4V; Vo = -30dB | V _{CC} /2 -1 | V _{CC} /2 -075 | V _{CC} /2 -0.5 | V |
| VT _{ST-BY} | St-by Threshold | | 0.8 | 1.3 | 1.8 | V |
| I _{ST-BY} | St-by Current V6 = GND | | | | 100 | μA |
| e _N | Total Output Voltage | A Curve; f = 20Hzto 20KHz | | 150 | | μV |

APPLICATION SUGGESTION**STAND-BY AND MUTE FUNCTIONS****Figure 2. Microprocessor Driving Signals**

The St-by and mute terminals are tied together and they are connected to the supply line via an external voltage divider.

The device is switched-on/off from the supply line and the external capacitor C4 is intended to delay the St-by and mute threshold exceeding, avoiding "Popping" problems.

Figure 3. Stand-alone low-cost Application

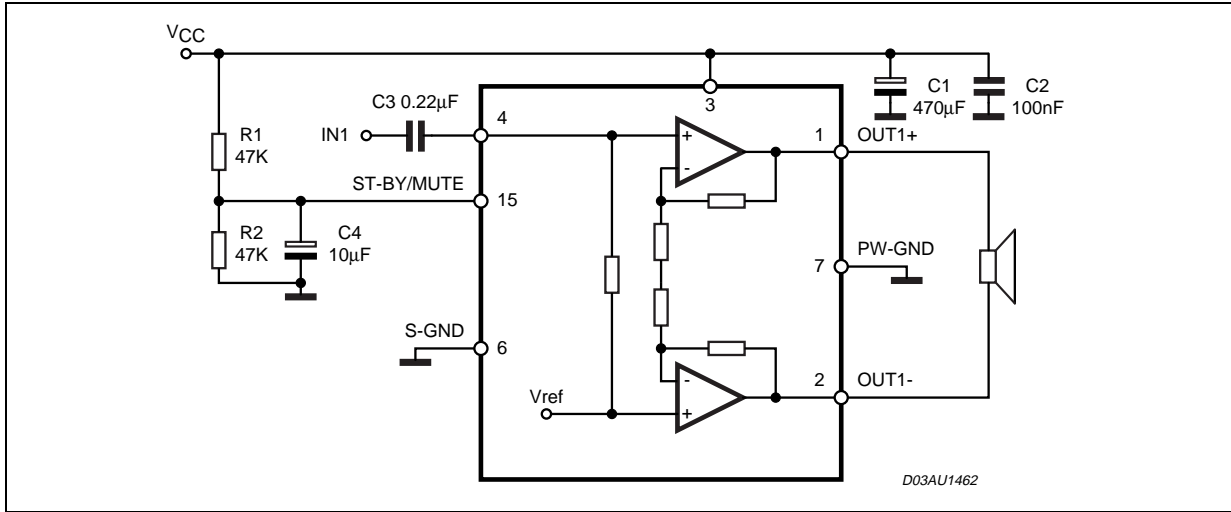


Figure 4. Distortion vs Ouput Power

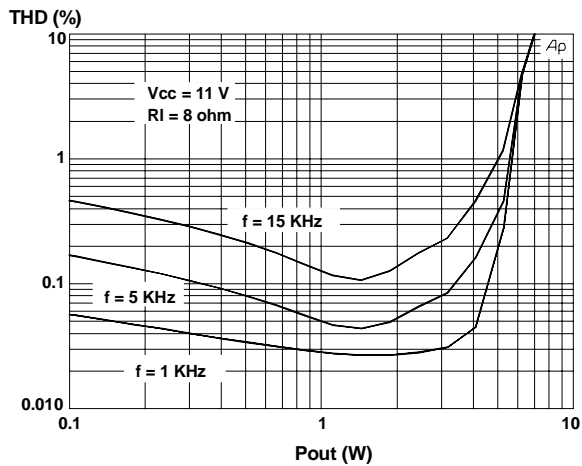


Figure 6. Distortion vs. Frequency

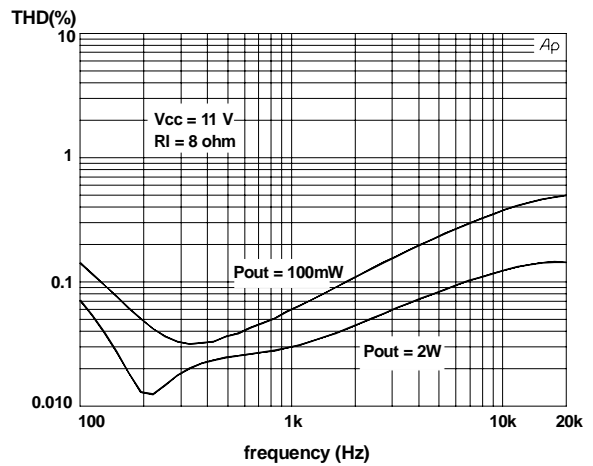


Figure 5. Distortion vs Ouput Power

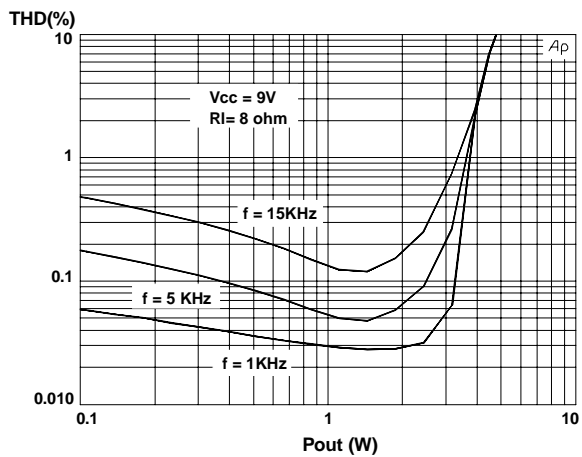


Figure 7. Gain vs Frequency

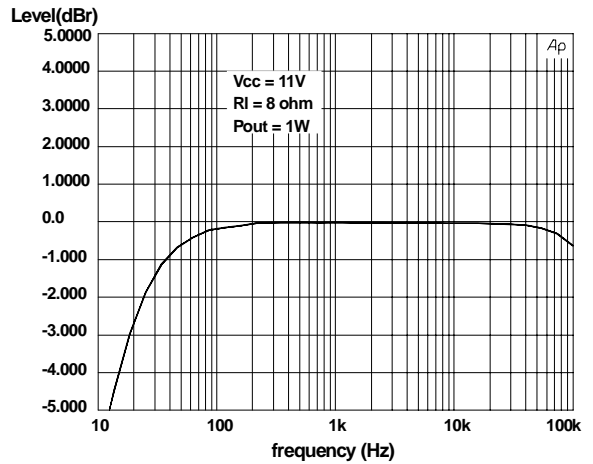


Figure 8. Output Power vs. Supply Voltage

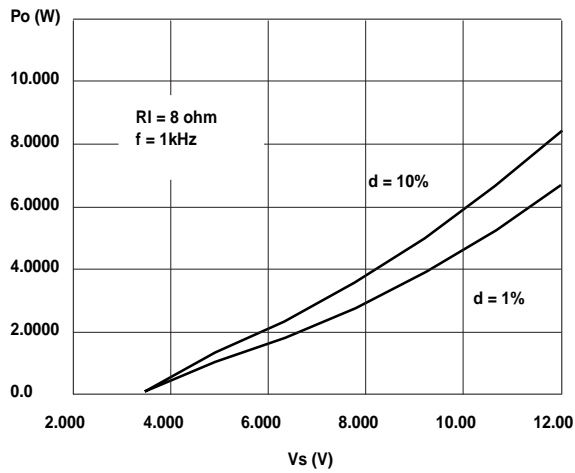


Figure 10. Mute & Stand-By Attenuation vs. $V_{pin.5}$

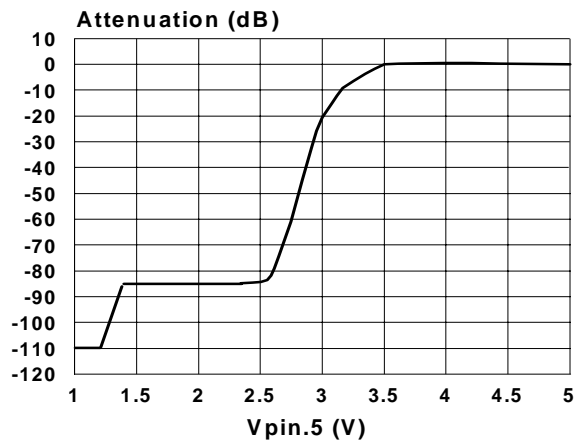


Figure 9. P_{tot} Dissipation & Efficiency vs. P_{out}

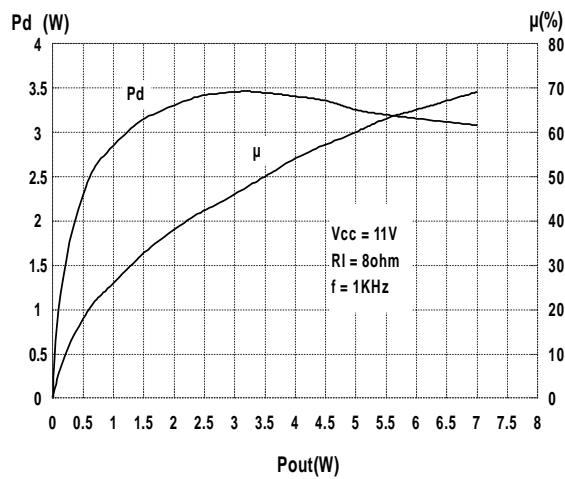


Figure 11. Quiescent Current vs. Supply Voltage

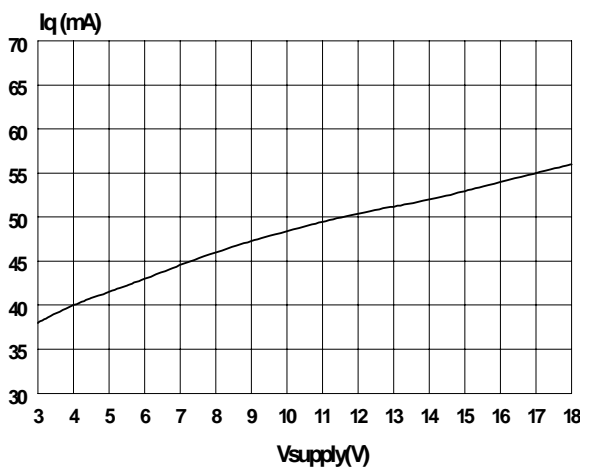


Figure 12. PC Board Component Layout

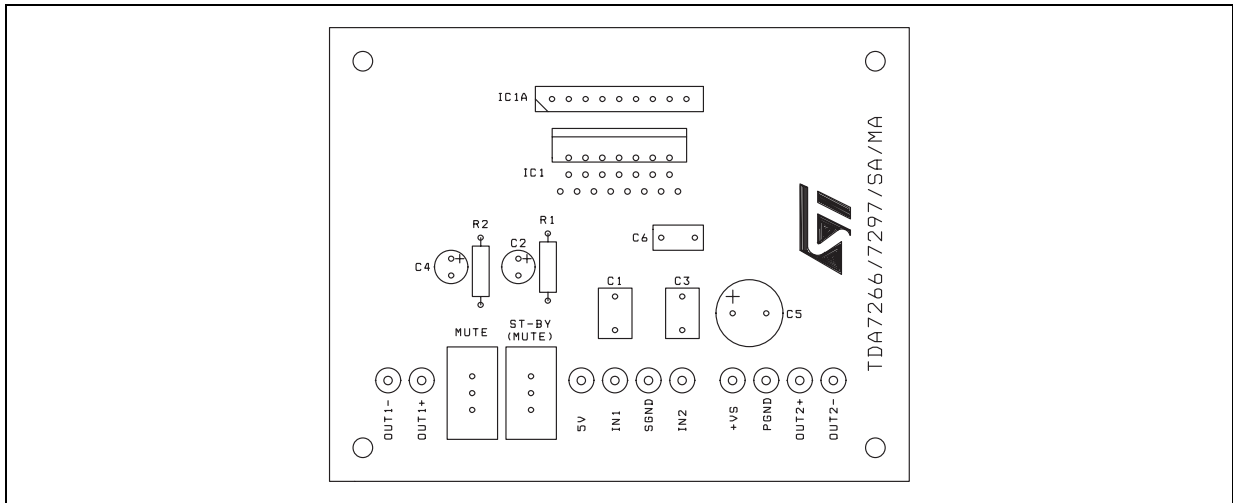


Figure 13. Evaluation Board Top Layer Layout

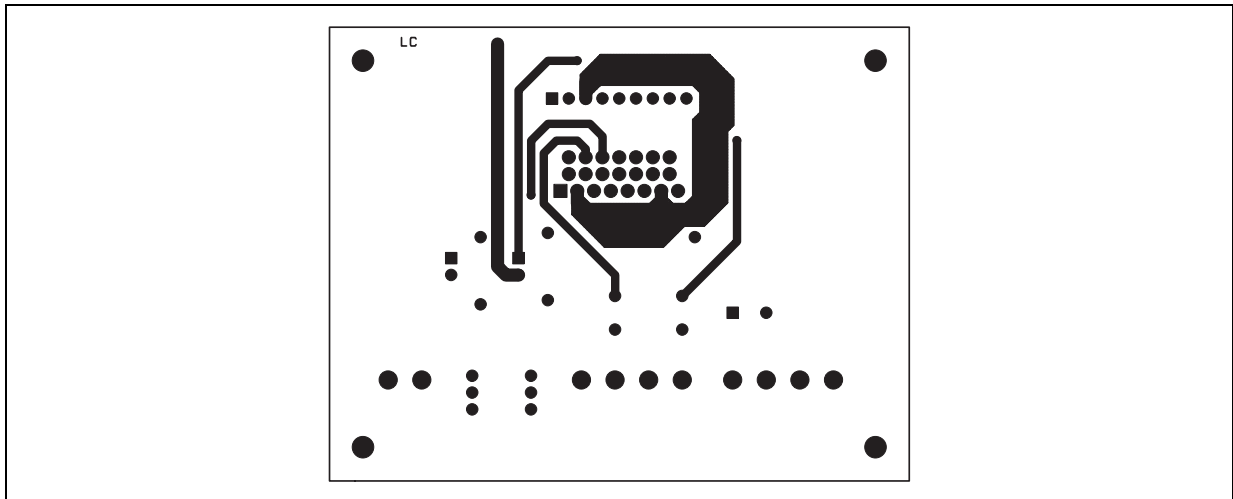
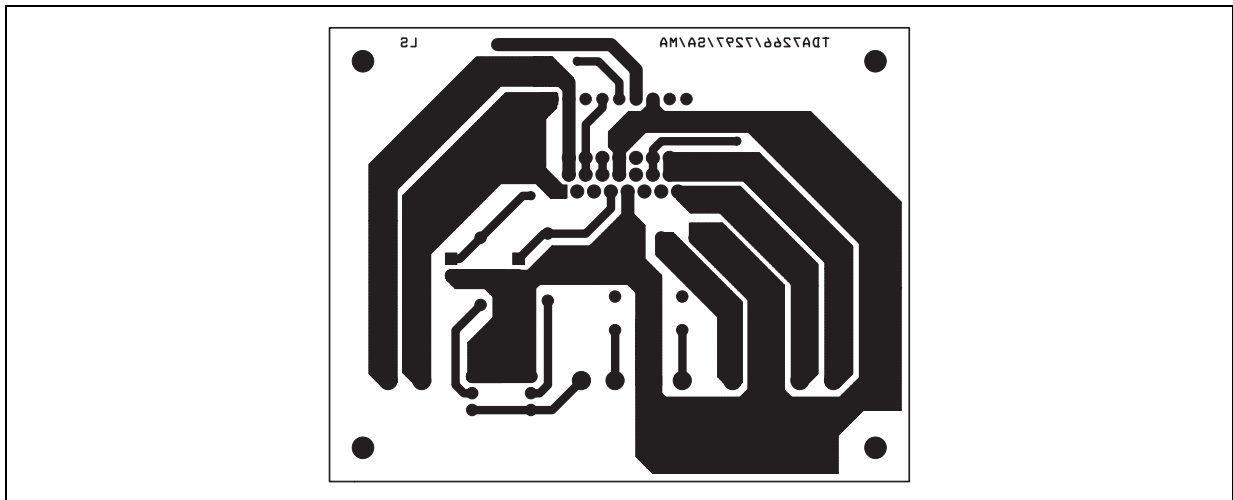


Figure 14. Evaluation Board Bottom Layer Layout



HEAT SINK DIMENSIONING:

In order to avoid the thermal protection intervention, that is placed approximatively at $T_j = 150^\circ\text{C}$, it is important the dimensioning of the Heat Sink R_{Th} ($^\circ\text{C}/\text{W}$).

The parameters that influence the dimensioning are:

- Maximum dissipated power for the device (P_{dmax})
- Max thermal resistance Junction to case ($R_{Th\ j-c}$)
- Max. ambient temperature $T_{amb\ max}$
- Quiescent current I_q (mA)

Example:

$V_{CC} = 11\text{V}$, $R_{load} = 80\text{ohm}$, $R_{Th\ j-c} = 9\ ^\circ\text{C}/\text{W}$, $T_{amb\ max} = 50^\circ\text{C}$

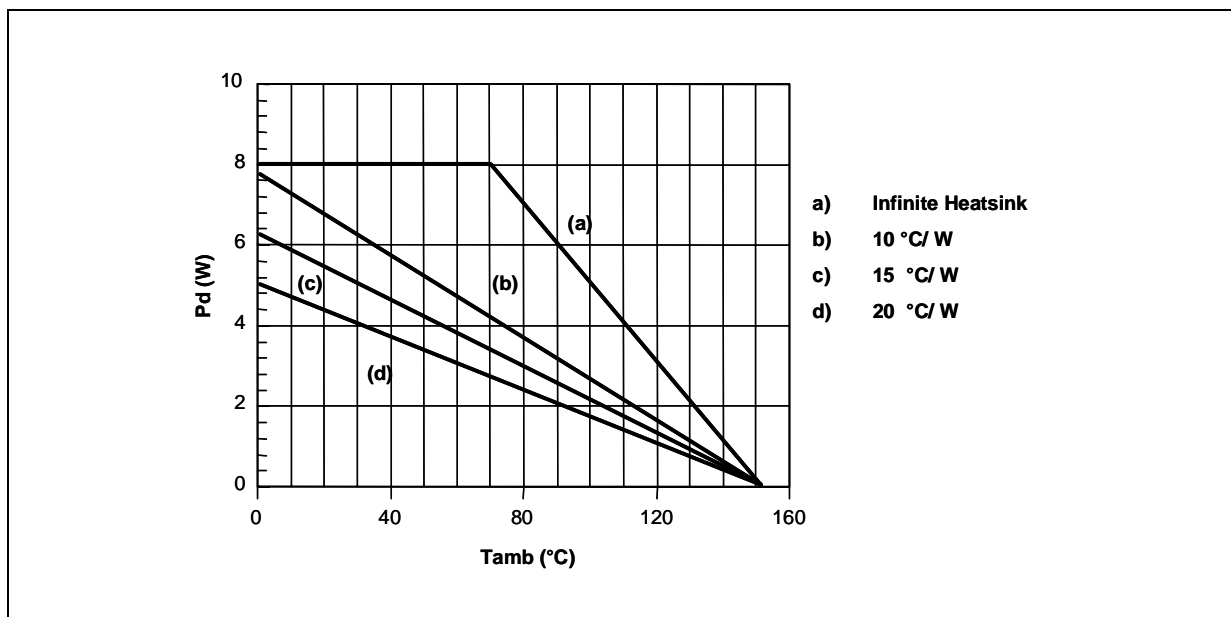
$$P_{dmax} = (N^\circ \text{ channels}) \cdot \frac{V_{CC}^2}{\Pi^2 \cdot \frac{R_{load}}{2}} + I_q \cdot V_{CC}$$

$$P_{dmax} = 1 \cdot (3) + 0.5 = 3.5\text{W}$$

$$(\text{Heat Sink}) R_{Th\ c-a} = \frac{150 - T_{amb\ max}}{P_{d\ max}} - R_{Th\ j-c} = \frac{150 - 50}{3.5} - 9 = 19.5^\circ\text{C}/\text{W}$$

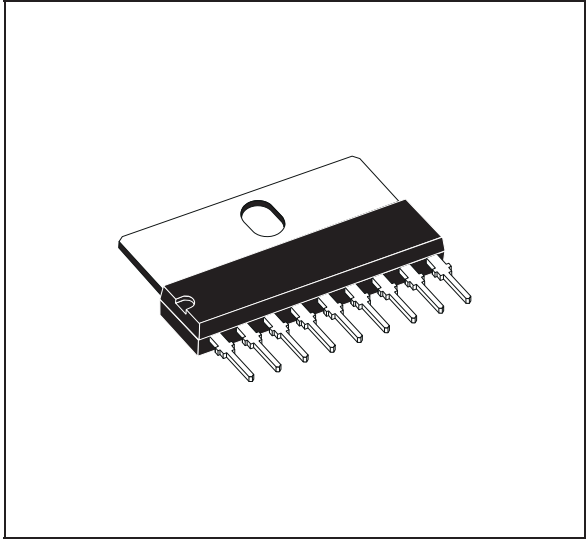
In figure 15 is shown the Power derating curve for the device.

Figure 15. Power derating curve

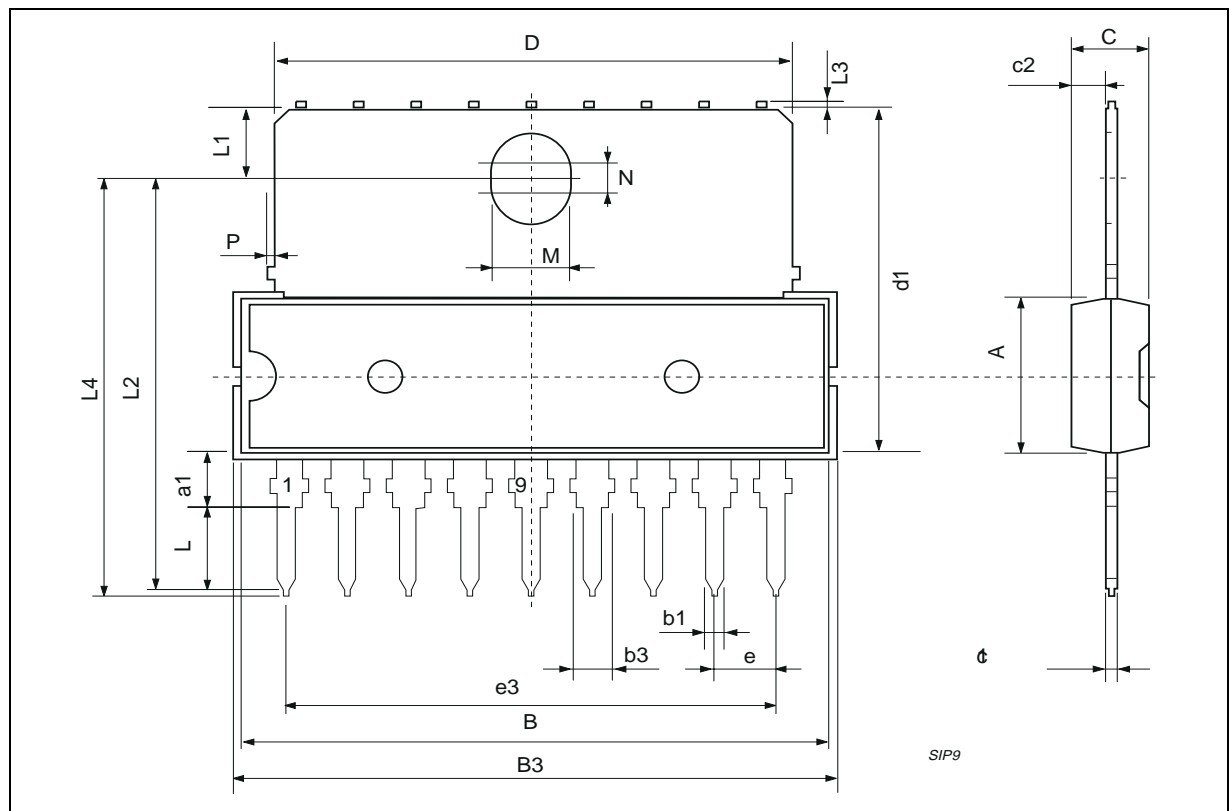


| DIM. | mm | | | inch | | |
|------|------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | | | 7.1 | | | 0.280 |
| a1 | 2.7 | | 3 | 0.106 | | 0.118 |
| B | | | 23 | | | 0.90 |
| B3 | | | 24.8 | | | 0.976 |
| b1 | | 0.5 | | | 0.020 | |
| b3 | 0.85 | | 1.6 | 0.033 | | 0.063 |
| C | | 3.3 | | | 0.130 | |
| c1 | | 0.43 | | | 0.017 | |
| c2 | | 1.32 | | | 0.052 | |
| D | | | 21.2 | | | 0.835 |
| d1 | | 14.5 | | | 0.571 | |
| e | | 2.54 | | | 0.100 | |
| e3 | | 20.32 | | | 0.800 | |
| L | 3.1 | | | 0.122 | | |
| L1 | | 3 | | | 0.118 | |
| L2 | | 17.6 | | | 0.693 | |
| L3 | | | 0.25 | | | 0.010 |
| L4 | 17.4 | | 17.85 | 0.685 | | 0.702 |
| M | | 3.2 | | | 0.126 | |
| N | | 1 | | | 0.039 | |
| P | | | 0.15 | | | 0.006 |

OUTLINE AND MECHANICAL DATA



SIP9



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